

Title (en)
EVAPORATION SOURCE WITH HEAT SHIELD ASSEMBLY

Title (de)
VERDAMPFUNGSQUELLE MIT HITZESCHILDANORDNUNG

Title (fr)
SOURCE D'ÉVAPORATION AVEC ENSEMBLE ÉCRAN THERMIQUE

Publication
EP 3585922 A1 20200101 (EN)

Application
EP 18705008 A 20180220

Priority
• EP 17157230 A 20170221
• EP 2018054145 W 20180220

Abstract (en)
[origin: WO2018153857A1] A modular demountable low-temperature high-output linear evaporation source (100) for depositing a semi-metal source material (75), in particular Se, on a substrate (50), the evaporation source comprising: a crucible (201) comprising: a base (203); a first plurality of walls (202) surrounding an interior region (204) of the crucible (201), the plurality of walls (202) including a first end wall (2021), a second end wall (2022) opposite to the first end wall (2021), a first side wall (2023), and a second side wall (2024) opposite to the first side wall (2023); a heat shield assembly (700) that comprises: a frame (740) a plurality of side wall portions (710) disposed around and spaced apart from the thermal isolation assembly (500), each side wall portion (710) folded over the frame (740) and including an outer section (711) disposed outside of the frame (740), an inner section (712) disposed inside the frame (740) and a ledge (714) extending inwardly from a bottom (718) of the outer section (711); a lid portion (730) disposed on the side wall portions (710); and a base portion (720) disposed on the ledge (714) of the side walls portions (710).

IPC 8 full level
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CPC (source: EP)
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Citation (search report)
See references of WO 2018153857A1

Cited by
CN112768374A

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Designated extension state (EPC)
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